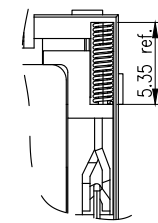
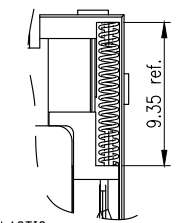
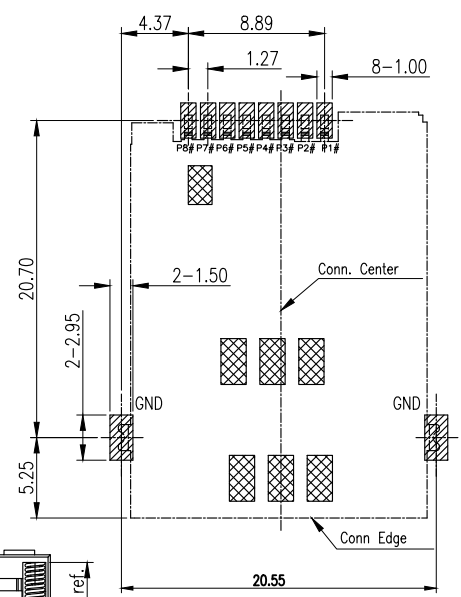
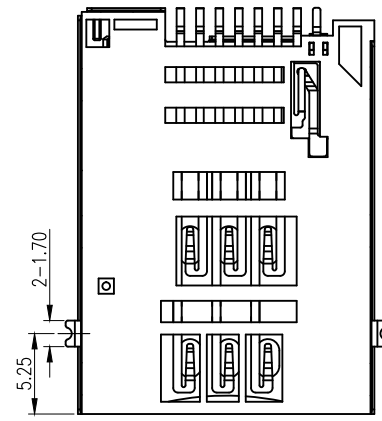
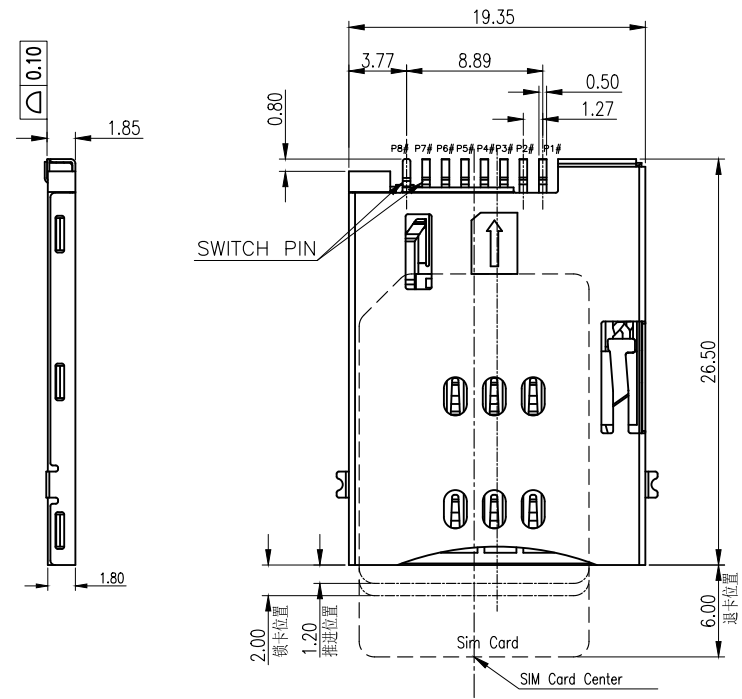
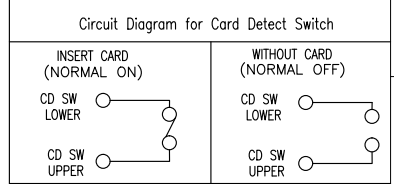


REV:	ECN. NO.	NAME	DATE

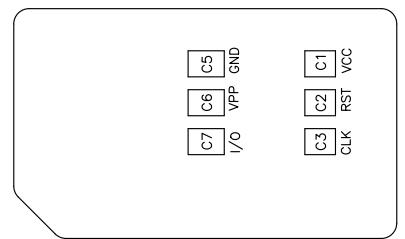


RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA



- NOTES:
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC
CONTACT: COPPER ALLOY
SHELL: STEEL
 - FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
MATE-TIN PLATED ON SOLDER TAILS WITH ENTIRE CONTACT UNDERPLATED NICKEL.
SHELL: GOLD FLASH PLATED ON SOLDER TAILS
 - INFRARED REFLOW SOLDERING: 10sec. Min. at 260[±]0



SIM 示意图
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

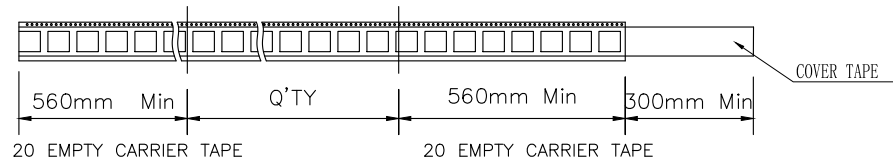
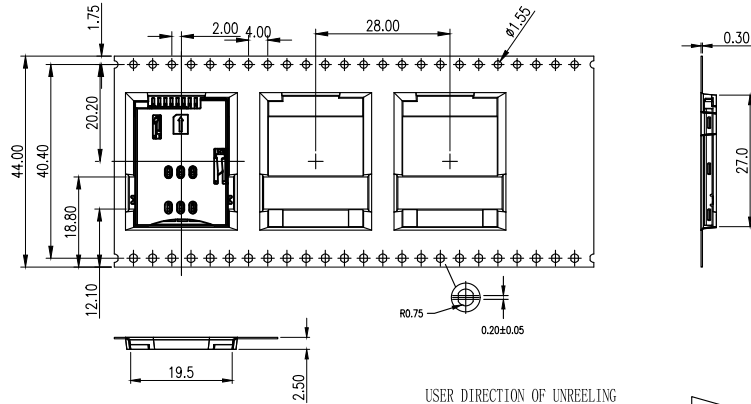
RoHS Compliant



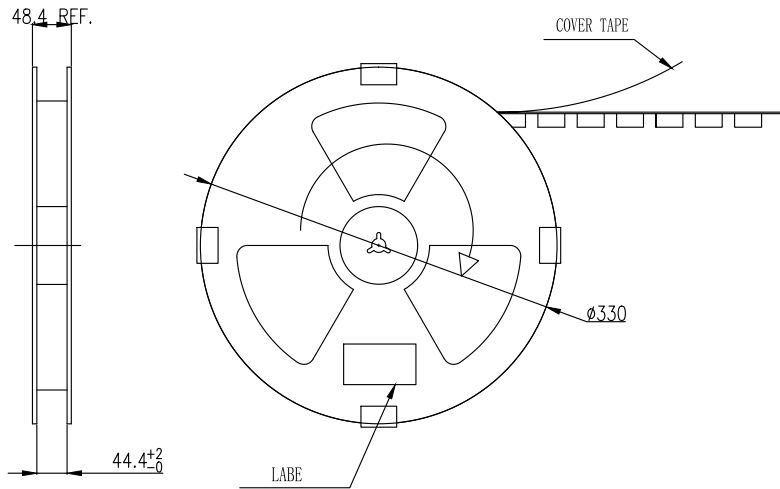
FOR YOUR VITAL CONNECTION

MILLIMETERS X.° ± 2° .X ± 0.30 .XX ± 0.20 .XXX ± 0.10	INCH X.° ± 2° .X ± 0.012 .XX ± 0.008 .XXX ± 0.004	TITLE:	SIM CARD PUSH 外焊H=1.80 LCP黑胶 端子 C5210 外壳不锈钢	
DRAWN BY:	Zou Long	PART NO:	VTC102011322	REV: A
CHECKED BY:	Bob	SIZE: A4	UNIT:mm	SHEET:1 OF 2 FCN: E1
APPROVED BY:	QPF	PROJECTION		http://www.vitalconn.com

<图一>



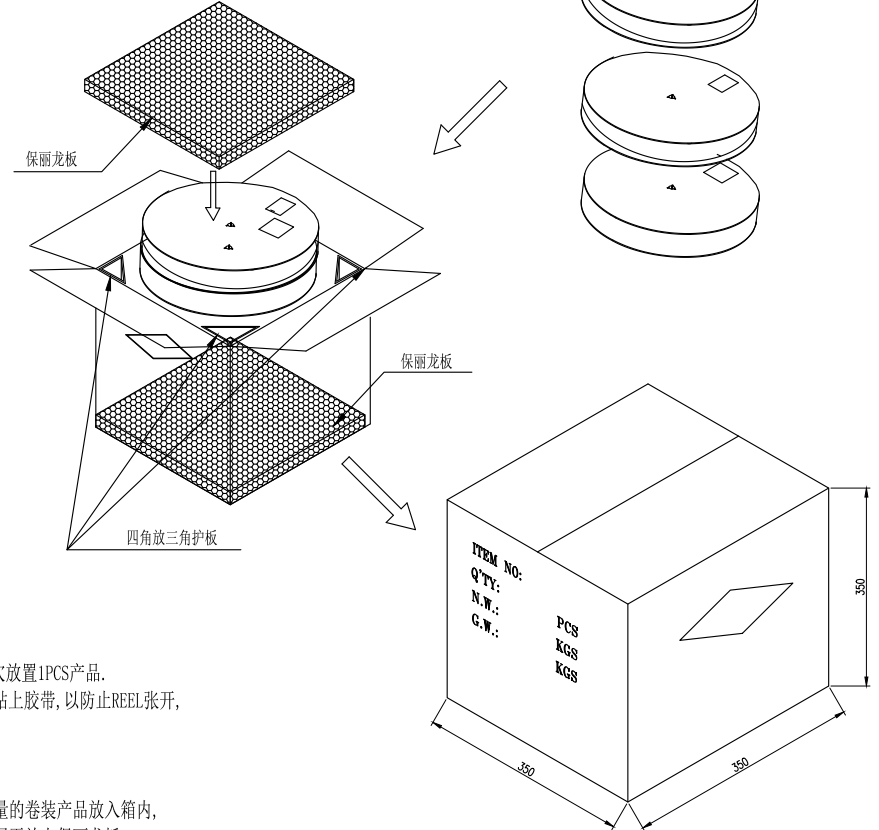
<图二>



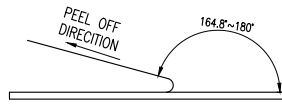
<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>




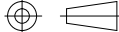
COVER TAPE PEELING FORCE:20gf~120gf



NOTE:

1. 依<图一>示放置产品于下载中, 每次放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点上贴胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

RoHS Compliant

MILLIMETERS X.° ± 2° .X ± 0.30 .XX ± 0.20 .XXX ± 0.10	INCH X.° ± 2° .X ± 0.012 .XX ± 0.008 .XXX ± 0.004	 FOR YOUR VITAL CONNECTION	
DRAWN BY: Zou Long		TITLE:	SIM CARD PUSH 外焊H=1.80 LCP黑胶 端子 C5210 外壳不锈钢
CHECKED BY: Bob		PART NO:	VTC102011322 REV: A
APPROVED BY: QPF		SIZE: A4	UNIT:mm SHEET:2 OF 2 FCN: E1
PROJECTION		 http://www.vitalconn.com	